

UNITED STATES PATENT AND TRADEMARK OFFICE
CERTIFICATE OF CORRECTION

PATENT NO. : 6,946,039 B1
APPLICATION NO. : 09/705101
DATED : September 20, 2005
INVENTOR(S) : Segal et al.

Page 1 of 1

It is certified that error appears in the above-identified patent and that said Letters Patent is hereby corrected as shown below:

Item (56) References Cited, Other Publications – Insert “R.Z. Valiev et al., “Plastic deformation of alloys with submicron-grained structure”, Materials Science and Engineering, A137 (1991) pp. 35-40.

Column 3, line 47 – Replace “comprise” with --comprises--.

Column 4, line 40 – Replace “a an b” with --a and b--.

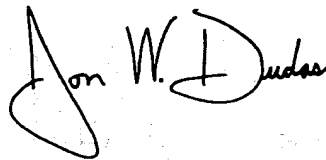
Column 12, line 12 – Replace “insure” with --ensure--.

Column 14, line 16 – After “can” insert --be--.

Column 14, line 56 – Replace “5h)” with --5h--.

Signed and Sealed this

Twenty-second Day of August, 2006

A handwritten signature in black ink, appearing to read "Jon W. I. Dudas". The signature is stylized with a large, looped initial "J" and a distinct "I" before the last name.

JON W. DUDAS
Director of the United States Patent and Trademark Office